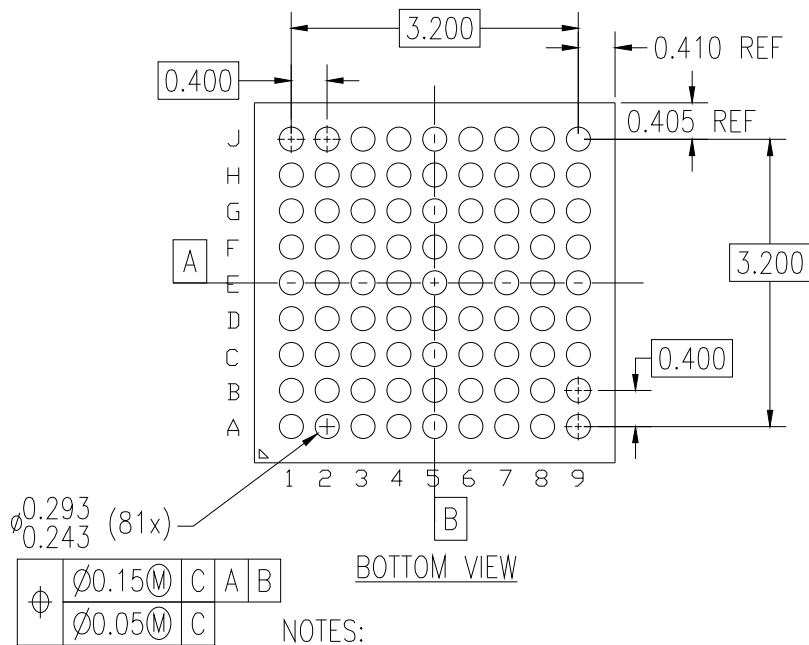
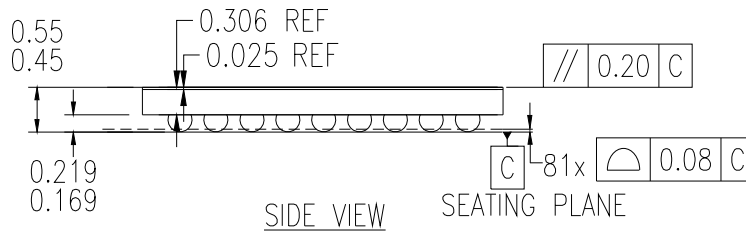
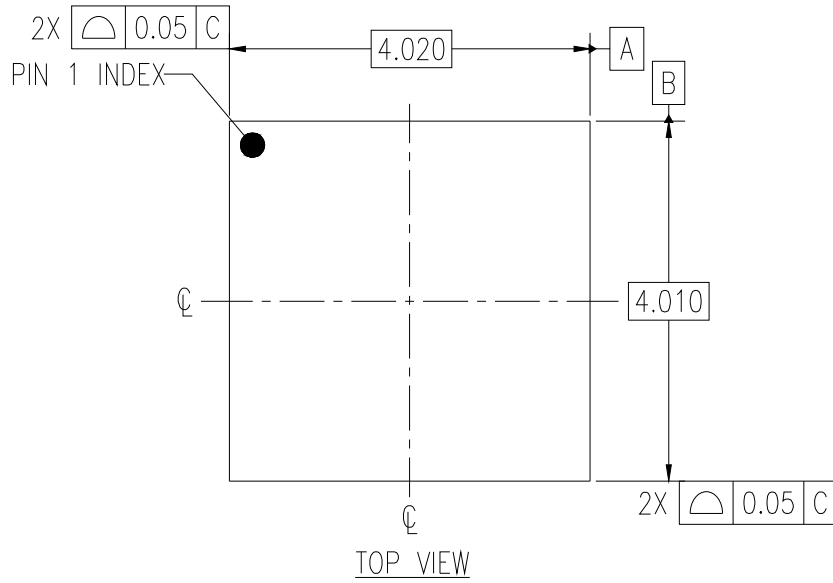


81-DSBGA, Package Outline Drawing

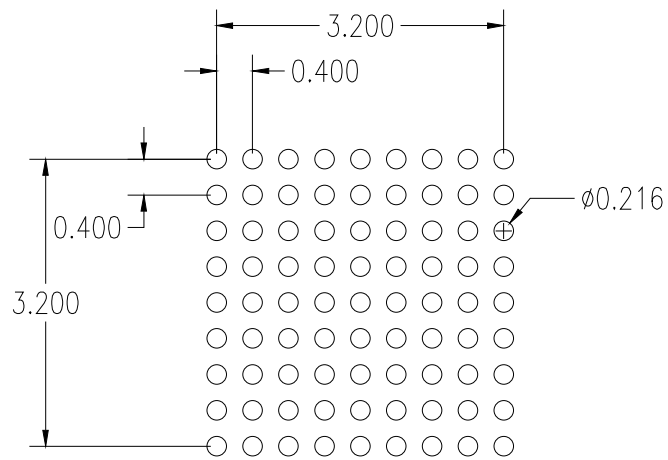
4.02 x 4.01 x 0.5 mm Body, 0.4mm Pitch

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NOTES:

1. ALL DIMENSION ARE IN MM. ANGLES IN DEGREES.
2. DIE STEP SIZE 4.06 x 4.05 MM.



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

1. ALL DIMENSIONS ARE IN MM, ANGLES IN DEGREES.
2. TOP DOWN VIEW, AS VIEW ON PCB.
3. NSMD LAND PATTERN ASSUMED.
4. LAND PATTERN RECOMMENDATION AS PER IDT DSBGA APPLICATION NOTE.

Package Revision History		
Date Created	Rev No.	Description
March 10, 2020	Rev 01	Add Dimension on edge of solderball
April 1, 2019	Rev 00	Initial Release